

6

5

4

3

2

1

D

D

C

C

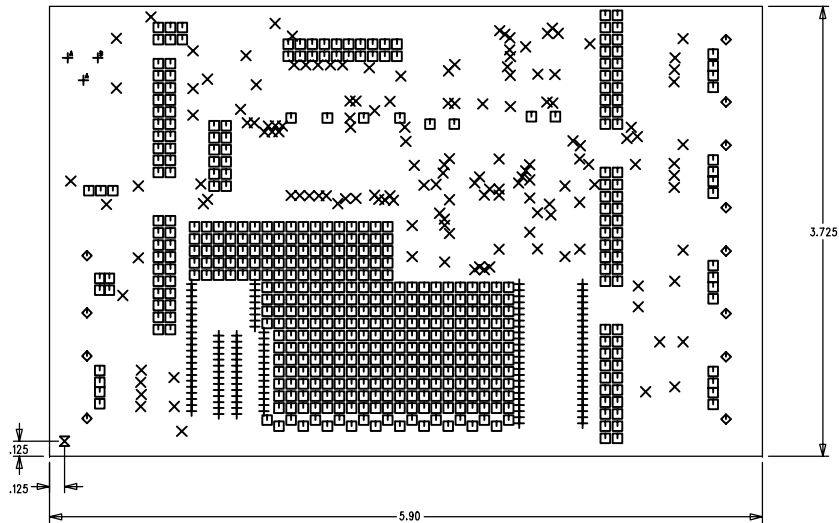
B

B

A

A


REVISION RECORD			
LTR	DESCRIPTION:	APPROVED	DATE
*A	RELEASE FOR BUILD	CXN	08/27/01
*B	CHANGE NET NCS: REMOVE FROM CONNECTOR P4-16 ADD TO CONNECTOR P1-4.	XDH	04/01/02
*C	CHANGE J4 ADDED GROUND TO PIN 3. REMOVED SLOTS AND DETAIL A. ADDED DRILL HOLES.	OMD	05/28/02



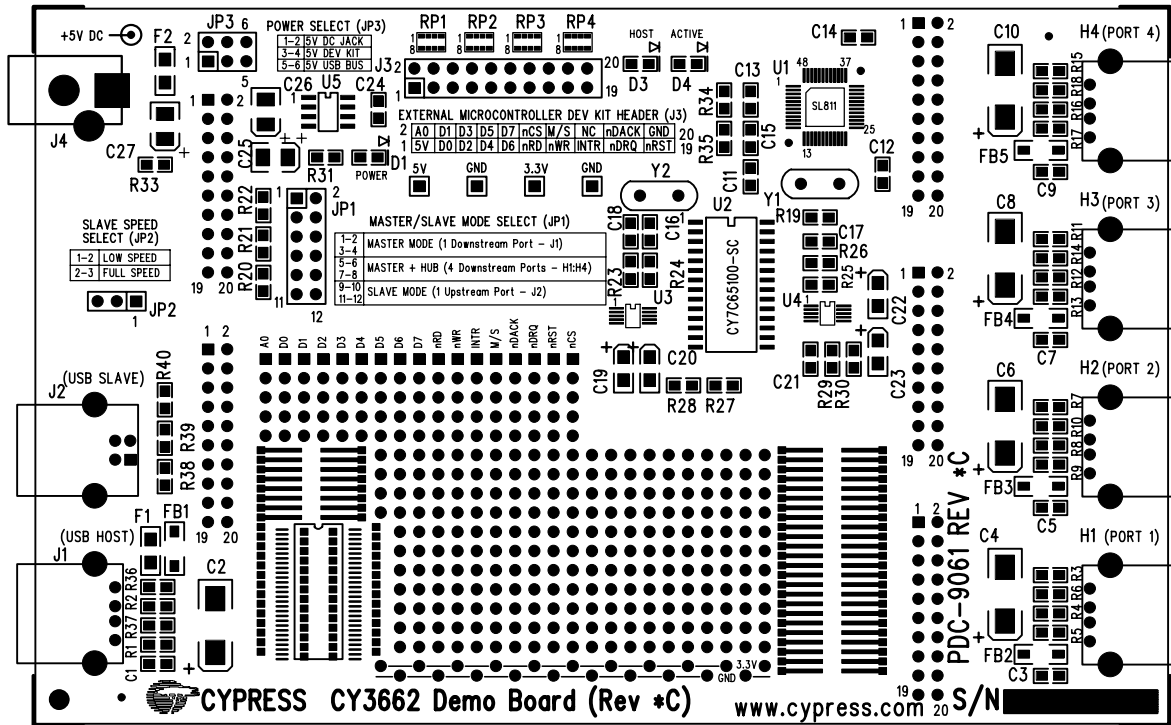
SIZE	QTY	SYM	PLTD
24	120	+	PLTD
16	151	X	PLTD
40	503	□	PLTD
91	12	◇	PLTD
125	1	⊗	NPLTD
120	2	A	PLTD
140	1	B	PLTD

- 13. Minimum trace width is .008 maximum .040 minimum spacing trace to trace .008.
- 12. .060 maximum on all inside corners.
- 11. Dimensions and tolerances per ANSI Y14.5M
- 10. Fabricate boards in accordance with IPC-6012, Class 2 products.
- 9. Board shall meet the requirements of UL796 with a flammability rating of 94V-D vendor's logo or designation shall be on solder side of board.
- 8. Remove all burrs and break sharp edges .015 Max.
- 7. Silkscreen component side of board using permanent, non-conductive, epoxy base ink; white in color.
- 6. Warp or Twist of board shall not exceed .010 inch per inch.
- 5. Boards are to be manufactured using the solder-mask over bare copper (SMOBC) process. Solder-mask shall be Liquid Photoimageable (LPI), semi gloss green in color; and must meet the requirements of IPC-SM-840, for Class 'T' products.
- 4. Conductor widths and spacing shall be within +/- .10X of artwork originals.
- 3. All holes shall be located within .003 Diameter of true position layer to layer registration shall be within .003. All holes surrounded by land shall have a minimum annular ring of .003.
- 2. Unless otherwise specified, all hole dimensions apply after plating. Specified hole sizes are to be held within a tolerance of +/- .003. Copper plating on hole walls shall be .0008 average minimum, and .0007 minimum
- 1. Material: Plastic Sheet, Laminated Glass-Epoxy, as per MIL-SH-13949H/4, Copper clad with 1oz./sq.' on all "Signal" layers, and 2oz./sq.' on "Plane" layers. "Outer" layers to have a minimum of 1oz./sq.' finished. Laminate using pre-preg materials as per MIL-S-13949H/12. Finished overall board thickness to be .062" +/- .007".

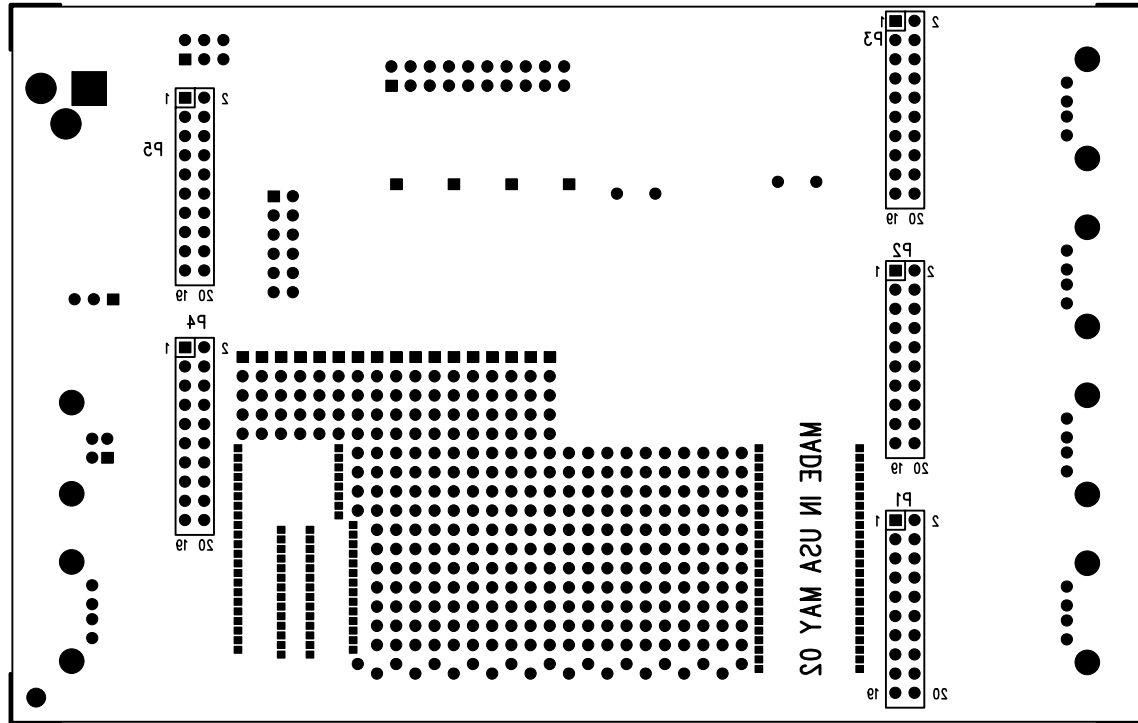
Notes: Unless Otherwise Specified

COMPANY:  CYPRESS SEMICONDUCTOR PCB DESIGN 15050 Avenue of Science, San Diego CA 92128	
TITLE: CY3662 DEMO BOARD (EZ-811)	
MODEL: CY3662	DRAWING NO: PDC-9061
REV: *C	
SCALE: 1/1	SHEET: 1 OF 1

DRAWN: M.KINGSLEY	DATED: 01-21-02
CHECKED: M.DEJULIO	DATED: 04-03-02
ENG: CHER NG	DATED: 08-27-01
RELEASED:	DATED:



CYPRESS SEMICONDUCTOR		ADDRESS: 583 Orchard Road Forum #11-03, Singapore 0923 Tel: (858) 613-7900 Fax: (858) 676-6896	
ENGINEER: Cher Ng PHONE: +65 735-0338	TITLE: CY3662 DEMO BOARD	FILE NAME: PDC-9061-C.PCB	
PCB DESIGNER: Mike Kingsley PHONE: (858) 613-7931	PART NO.: PDC-9061	REV: *C	DATE: 28-MAY-02
SILKSCREEN COMPONENT SIDE		GERBER: SLKCP9061.pho	



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PCB DESIGNER: Mike Kingsley PHONE: (858) 613-7931	PART NO.: PDC-9061	REV: *C	DATE: 28-MAY-02
SILKSCREEN SOLDER SIDE		GERBER: SLKSD9061.pho	